Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: J7A 006 VDFN 2.0x2.5mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling
										e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	5.03	(mg) Total	Mold Compound	% ot Total Weight	40.24
Silica Fused	60676-86-0	Mold Compound	37,222	4.653	372,220		Silica Fused	60676-86-0	92.50	
Epoxy Resin	Trade secret	Mold Compound	1.408	0.176	14,084		Epoxy Resin	Trade secret	3.50	
Phenol Resin	Trade secret	Mold Compound	1.408	0.176	14,084		Phenol Resin	Trade secret	3.50	
Carbon Black	1333-86-4	Mold Compound	0.201	0.025	2,012		Carbon Black	1333-86-4	0.50	
Copper	7440-50-8	Lead Frame	46.488	5.811	464,875			Total	100.00	
Iron	7439-89-6	Lead Frame	0.070	0.009	699	5.82	(mg) Total	Lead Frame	% of Total Weight	46.59
Phosphorous	7723-14-0	Lead Frame	0.019	0.002	186		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.014	0.002	140		Iron	7439-89-6	0.15	
Silver	7440-22-4	Die Attach	0.754	0.094	7,540		Phosphorous	7723-14-0	0.04	
Silica Fused	60676-86-0	Die Attach	0.657	0.082	6,574		Zinc (Metal)	7440-66-6	0.03	
Epoxy Resin	120206-26-0	Die Attach	0.440	0.055	4,404			Total	100.00	
Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6	Die Attach	0.148	0.019	1,482	0.25	(mg) Total	Die Attach	% of Total Weight	2.00
Silicon	7440-21-3	Chip (Die)	9.170	1.146	91,700		Silver	7440-22-4	37.70	
Gold	7440-57-5	Wire Bond	0.750	0.094	7,500	1	Silica Fused	60676-86-0	32.87	
Nickel	7440-02-0	Plating on external leads (pins)	1.125	0.141	11,250		Epoxy Resin	120206-26-0	22.02	
							Poly(Bisphenol A-co-	25068-38-6		
Palladium	7440-05-3	Plating on external leads (pins)	0.063	0.008	625		epichlorohydrin)		7.41	
Gold	7440-57-5	Plating on external leads (pins)	0.063	0.008	625			Total	100.00	
Gold	7440-57-5	Plating on external leads (pins)  TOTALS:	0.063 <b>100.000</b>	0.008 <b>12.500</b>	625 1,000,000	1.15	Total (mg)	Total Chip (Die)	100.00 % of Total Weight	9.17
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